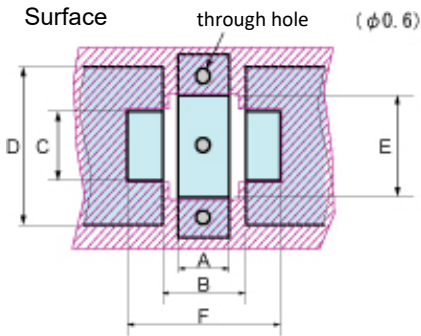


Handling Precautions

■ Soldering (Exclusively for reflow soldering. Not applicable for flow soldering)

1. Basic Design

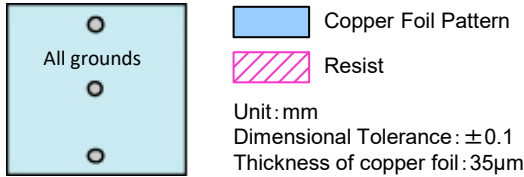
Recommended Board Pattern (Unit:mm)



Type	A	B	C	D	E	F
CTH20 Type	0.8	1.5	1.2	2.5	1.8	2.8
CTH30 Type	1.5	2.5	2.2	4.0	3.2	4.8
CTH32 Type	1.5	2.5	3.0	6.0	5.0	4.8

* D dimension presupposes the rated current.

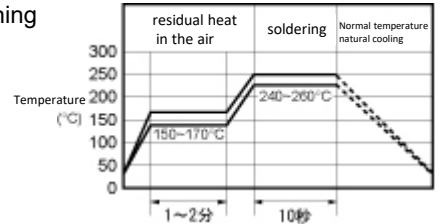
Bottom Side



2. General Cautions for Soldering

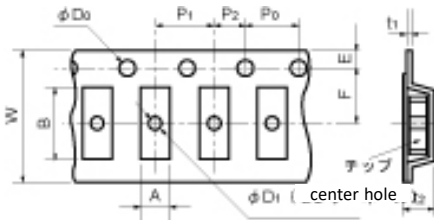
- (1) High soldering temperature and long soldering time can cause leaching of the termination, decrease in adhesion strength, and a drop in capacitance value, etc.
- (2) For soldering, please refer to the soldering curves below.

Reflow Soldering Temperature Patterns (Lead-free Solder)



■ Taping

Tape Dimensions (Unit:mm)



Type	A	B	W	F	E	P1	P2	P0	D0	D1	T1	t2	Hole
CTH20	1.45±0.2	2.3±0.2	8.0 ±0.2	3.50 ±0.05	1.75 ±0.1	4.0 ±0.1	2.00 ±0.05	4.0 ±0.1	Φ1.5 +0.1 -0	Φ1.15 ±0.5	Less than 0.6	Less than 3.0	Square embossed hole
CTH30	2.0±0.2	3.6±0.2											
CTH32	2.9±0.2	3.6±0.2											

■ Package Qty

Type	Taping Qty
CTH20	2,000pcs / reel
CTH30	2,000pcs / reel
CTH32	1,000pcs / reel